

02-24-2000



Docket No. 0756-2063

101275097

To the Honorable Commissioner of Patent and Trademark: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies): SHUNPEI YAMAZAKI; HISASHI OHTANI; TOSHIJI HAMATANI

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Semiconductor Energy Laboratory Co., Ltd.

Address: 398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Jaapn

Additional name(s) & addresses(es) attached? ☐ Yes ☒ No



3. Name of Conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: _____

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

Title: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

A: Patent Application No. 09/436,984

B: Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Nixon Peabody LLP

Street Address: 8180 Greensboro Drive, Suite 800

City: McLean State: Virginia ZIP 22102

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):\$ 40

☒ Enclosed
☐ Authorized to be charged to deposit account
☒ Authorized to charge any deficiency in the payment of the required fee(s) or credit any overpayment to Deposit Account No 19-2380.

8. Deposit Account Number: 19-2380

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Eric J Robinson

Name of Person Signing

Signature

Date

Total number of pages comprising cover sheet, attachments and document: 3

PATENT
REEL: 010594 FRAME: 0562

ASSIGNMENT

Serial No. 09/436,984

Filed 11/09/99

WHEREAS, Shunpei YAMAZAKI,

Hisashi OHTANI and

Insert Name(s)
of Inventor(s)

Toshiji HAMATANI

Insert Title of
Invention

(hereinafter designated as the undersigned) has (have) invented certain new and useful improvements in _____

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

Insert Date of
Signing of
Application

for which an application for Letters Patent of the United States of America has been executed by the undersigned on _____; and

WHEREAS, Semiconductor Energy Laboratory Co., Ltd.

Insert Name of
Assignee

Insert Address
of Assignee

of 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to the undersigned in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, the undersigned has (have) sold, assigned and transferred, and by these presents do sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America and its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America and its territories, dependencies and possessions, and in and to any and all divisions, reissues, continuations and extensions thereof for the full term or terms for which the same may be granted.

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or any continuation, division or reissue thereof or Letters Patent(s) or reissue patent issued thereon and to cooperate with the Assignee in every way possible in obtaining and producing evidence and proceeding with such interference.

The undersigned agree(s) to execute all papers and documents and to perform any act which may be necessary in connection with claims under or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks to issue any and all Letters Patents of the United States of America resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) the full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the law firm of Sixbey, Friedman, Leedom & Ferguson, P.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.

In witness whereof, this Assignment has been executed by the undersigned on the date(s) opposite the undersigned name(s).

Date 01/21/2000, Name of Inventor Shunpei Yamazaki (signature) (SEAL)
Shunpei YAMAZAKI
Date 01/22/2000, Name of Inventor Hisashi Ohtani (signature) (SEAL)
Hisashi OHTANI
Date 01/20/2000, Name of Inventor Toshiji Hamatani (signature) (SEAL)
Toshiji HAMATANI
Date _____, Name of Inventor _____ (signature) (SEAL)
Date _____, Name of Inventor _____ (signature) (SEAL)

(This assignment should preferably be acknowledged before a United States Consul or Notary Public. If not, then the execution by the Inventor(s) should be witnessed by at least two other persons who should sign here.)

Witness _____ (name) _____ (signature)
Witness _____ (name) _____ (signature)
Witness _____ (name) _____ (signature)